

THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Ho-Cheol LEE

Conf:

4619

Appl. No.:

10/803,043

Group:

2826

Filed:

March 18, 2004

Examiner:

Benjamin P.

SANDVIK

For:

SEMICONDUCTOR PACKAGE HAVING MULTIPLE EMBEDDED CHIPS

Customer Service Window Randolph Building 401 Dulany Street Alexandria, VA 22314

January 20, 2006

Mail Stop Issue Fee

AMENDMENT AFTER ALLOWANCE UNDER 37 C.F.R. § 1.312

Sir:

In reply to the Notice of Allowance mailed October 20, 2005, the following amendment and remarks are submitted under 37 C.F.R. §1.312 in connection with the above-identified application. Applicant requests entry of these into the record and further consideration culminating in a Supplemental Notice of Allowance.

Amendments to the Claims begin on page 2 of this Amendment; and Remarks begin on page 6 of this Amendment.

	Claims remaining after Amendment		Highest number previously paid for	-	Present extra
Total	18	-	18	=	0
Independent	3	-	3	=	0